

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A chip for a chip-containing portable article, ~~in particular an article of card format~~ the chip comprising a silicon substrate layer ~~whose~~ having an active face ~~has~~ with circuits integrated therein defining a central processor unit and memories, and an additional layer of silicon that is sealed to the active face of the silicon substrate layer by a sealing layer, the additional layer of silicon covering at least part of said active face, the additional layer of silicon ~~and~~ comprising physical means for providing physical protection against the action of electromagnetic radiation in the infrared range at a wavelength longer than 1  $\mu\text{m}$ .
2. (cancelled)
3. (cancelled)
4. (cancelled)
5. (previously presented) A chip according to Claim 1, wherein the physical means for providing physical protection against the action of electromagnetic radiation are silicon dopants.
6. (previously presented) A chip according to Claim 5, wherein the concentration of silicon dopants lies in the range  $10^{17}$  to  $10^{20}$  atoms per  $\text{cm}^3$ .
7. (previously presented) A chip according to Claim 5, wherein the silicon dopants are phosphorus or boron.
8. (cancelled)
9. (cancelled)
10. (previously presented) A chip according to Claim 1, wherein the physical means for providing physical protection against the action of electromagnetic radiation are formed by surface irregularities.
11. (cancelled)

12. (currently amended) A chip according to claim 10, wherein the surfaces  
irregularities are provided in the ~~bottom~~ face of the additional layer of silicon that  
is in contact with the sealing layer.
13. (currently amended) A chip according to Claim 10, wherein the surface  
irregularities are provided in the ~~top~~ face of the additional layer of silicon that is  
opposite to the face that is in contact with the sealing layer.
14. (currently amended) A chip according to Claim 1, wherein the physical means  
for providing physical protection against the action of electromagnetic radiation  
are formed by at least one ~~layer~~ deposition of metal on the additional layer of  
silicon.
15. (currently amended) A chip according to Claim 14, wherein the metal deposition  
~~layer~~ has a thickness greater than 50 Å.
16. (currently amended) A chip according to Claim 14, wherein the metal deposition  
is ~~placed~~ on the ~~bottom~~ face of the additional ~~layer~~ of silicon that is in contact  
with the sealing layer.
17. (currently amended) A chip according to Claim 14, wherein the metal ~~layer~~  
deposition is ~~placed~~ on the ~~top~~ face of the additional layer of silicon that is  
opposite to the face that is in contact with the sealing layer.
18. (cancelled)
19. (currently amended) A chip according to Claim 16, wherein the metal ~~layer~~  
deposition has a thickness of about 100 Å.
20. (new) A portable article provided with a chip that comprises a silicon substrate  
layer having an active face with circuits integrated therein defining a central  
processor unit and memories, the chip further comprising an additional layer of  
silicon that is sealed to the active face of the silicon substrate layer by a sealing  
layer, the additional layer of silicon covering at least part of said active face, the  
additional layer of silicon comprising physical means for providing physical  
protection against the action of electromagnetic radiation in the infrared range at  
a wavelength longer than 1 µm.